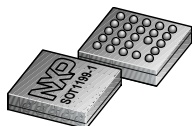


# SOT1199-1

VFBGA24, very thin fine-pitch ball grid array, 24 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

1 September 2025

Package information



## 1 Package summary

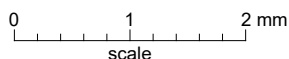
Terminal position code	B (bottom)
Package type descriptive code	VFBGA24
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	03-12-2013

Table 1. Package summary


Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	0.75	0.85	1	mm
package height	0.6	0.65	0.75	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	

## 2 Package outline

**SOT1199-1**



Unit		A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	max	1.00	0.25	0.75	0.35	3.1	3.1							
	nom	0.85	0.20	0.65	0.30	3.0	3.0	0.5	2	2	0.15	0.05	0.08	0.1
	min	0.75	0.15	0.60	0.25	2.9	2.9							

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1199-1		---				11-02-16 12-03-13

SOT1199-1

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VFBGA24, very thin fine-pitch ball grid array, 24 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

3 Soldering

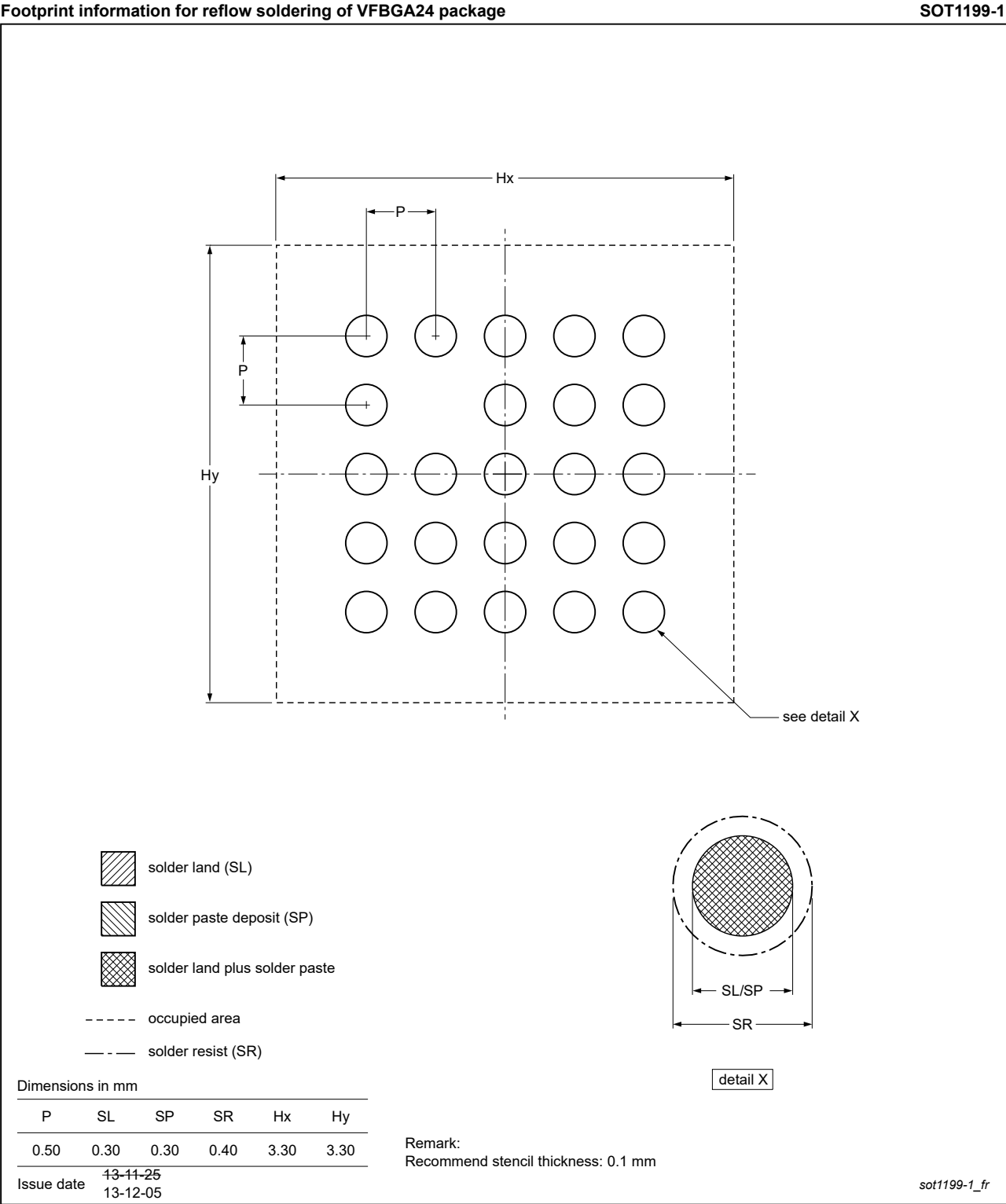


Figure 2. Reflow soldering footprint for VFBGA24 (SOT1199-1)

## 4 Legal information

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VFBGA24, very thin fine-pitch ball grid array, 24 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm  
body

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